OAI Model 800 Mask Aligner

The Model 800 is an optical topside and an optical and IR backside aligner. The Model 800 can be configured with a 365nm UV light source or a 265nm deep UV light source by simply changing the mirrors and objectives. The mask aligner tooling can accommodate substrates up to 3-inches square, and the wafer chuck is positioned to allow for easy loading and unloading.

Built on a vibration isolation platform, the fixed mask holder assembly guarantees alignment accuracy and repeatability. The operation is simplified using the easy-to-read, PLC touch-screen. Training time is short, an operator can learn to use the alignment tool effectively in less than one hour.

Features and Specifications:

- Designed for semiconductor, MEMS front side and backside lithography and nanotechnology
- Excellent for sub-micron printing
- Precision level-to-level mask alignment
- Four-camera optical system for double sided alignment
- Interchangeable mask holders and chucks
- User-defined & controlled substrate-to-mask pressure
- Soft, hard and vacuum contact printing capability